



Product Change Notification / JAON-16ISFI346

Date:

18-Mar-2015

PCN Type:

Manufacturing Change

Notification Subject:

CCB 1155.37 Final Notice: Qualification of palladium coated copper (PdCu) bond wire and 3280 die attach epoxy in selected products of the 90K, 120K and 121K wafer technologies available in 18L SOIC.

Notification Text:

PCN Status: Final notification

Microchip Parts Affected: See attachments of affected catalog part numbers (CPN) labeled as...PCN_JAON-16ISFI346_Affected_CPN.xls PCN_JAON-16ISFI346_Affected_CPN.pdf

Description of Change: Qualification of palladium coated copper (PdCu) bond wire and 3280 die attach epoxy in selected products of the 90K, 120K and 121K wafer technologies available in 18L SOIC package at MTAI assembly site.

NOTE: Selected products are non-automotive devices. Please review the affected CPN lists (attached) to identify the actual parts affected.

Pre Change: Gold wire and 8390A die attach epoxy

Post Change: Gold wire and 8390A die attach epoxy or PdCu wire and 3280 die attach epoxy

Impacts to Data Sheet: None

Reason for Change: To improve manufacturability and qualify PdCu bond wire at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: April 10, 2015 (date code: 1515)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices: Traceability code

Revision History:**February 18, 2015:** Issued initial notification.**March 16, 2015:** Issued final notification. Attached the qualification report.**March 18, 2015:** Revised the estimated first ship date from May 27, 2015 to April 10, 2015

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-16ISFI346_Qual_Report.pdf](#)
[PCN_JAON-16ISFI346_Affected_CPN.pdf](#)
[PCN_JAON-16ISFI346_Affected_CPN.xls](#)

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